

TM124BBK32F, TM124BBK32U 1048576 BY 32-BIT DYNAMIC RAM MODULE TM248CBK32F, TM248CBK32U 2097152 BY 32-BIT DYNAMIC RAM MODULE

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- **Organization**
TM124BBK32F . . . 1 048 576 × 32
TM248CBK32F . . . 2 097 152 × 32
- **Single 5-V Power Supply ($\pm 10\%$ Tolerance)**
- **72-Pin Single-In-Line Memory Module (SIMM) for Use With Socket**
- **TM124BBK32F – Utilizes Two 16-Megabit DRAMs in Plastic Small-Outline J-Lead (SOJ) Packages**
- **TM248CBK32F – Utilizes Four 16-Megabit DRAMs in Plastic Small-Outline J-Lead (SOJ) Packages**
- **Long Refresh Period**
16 ms (1024 Cycles)
- **All Inputs, Outputs, Clocks Fully TTL Compatible**
- **3-State Output**
- **Common $\overline{\text{CAS}}$ Control for Eight Common Data-In and Data-Out Lines in Four Blocks**
- **Enhanced Page-Mode Operation With $\overline{\text{CAS}}$ -Before-RAS (CBR), RAS-Only, and Hidden Refresh**

- **Presence Detect**
- **Performance Ranges:**

	ACCESS TIME t_{RAC} (MAX)	ACCESS TIME t_{AA} (MAX)	ACCESS TIME t_{CAC} (MAX)	READ OR WRITE CYCLE (MIN)
'124BBK32F-60	60 ns	30 ns	15 ns	110 ns
'124BBK32F-70	70 ns	35 ns	18 ns	130 ns
'124BBK32F-80	80 ns	40 ns	20 ns	150 ns
'248CBK32F-60	60 ns	30 ns	15 ns	110 ns
'248CBK32F-70	70 ns	35 ns	18 ns	130 ns
'248CBK32F-80	80 ns	40 ns	20 ns	150 ns

- **Low Power Dissipation**
- **Operating Free-Air Temperature Range**
0°C to 70°C
- **Gold-Tabbed Versions Available:[†]**
 - TM124BBK32F
 - TM248CBK32F
- **Tin-Lead (Solder) Tabbed Versions Available:**
 - TM124BBK32U
 - TM248CBK32U

description

TM124BBK32F

The TM124BBK32F is a 32-megabit dynamic random-access memory (DRAM) organized as four times 1 048 576 × 8 in a 72-pin SIMM. The SIMM is composed of two TMS418160DZ, 1 048 576 × 16-bit DRAMs, each in a 42-lead plastic SOJ package mounted on a substrate with decoupling capacitors. The TMS418160DZ is described in the TMS418160 data sheet. The TM124BBK32F SIMM is available in the single-sided BK-leadless module for use with sockets.

TM248CBK32F

The TM248CBK32F is a 64-megabit DRAM organized as four times 2 097 152 × 8 in a 72-pin SIMM. The SIMM is composed of four TMS418160DZ, 1 048 576 × 16-bit DRAMs, each in a 42-lead plastic SOJ package mounted on a substrate with decoupling capacitors. The TMS418160DZ is described in the TMS418160 data sheet. The TM248CBK32F SIMM is available in the double-sided BK-leadless module for use with sockets.

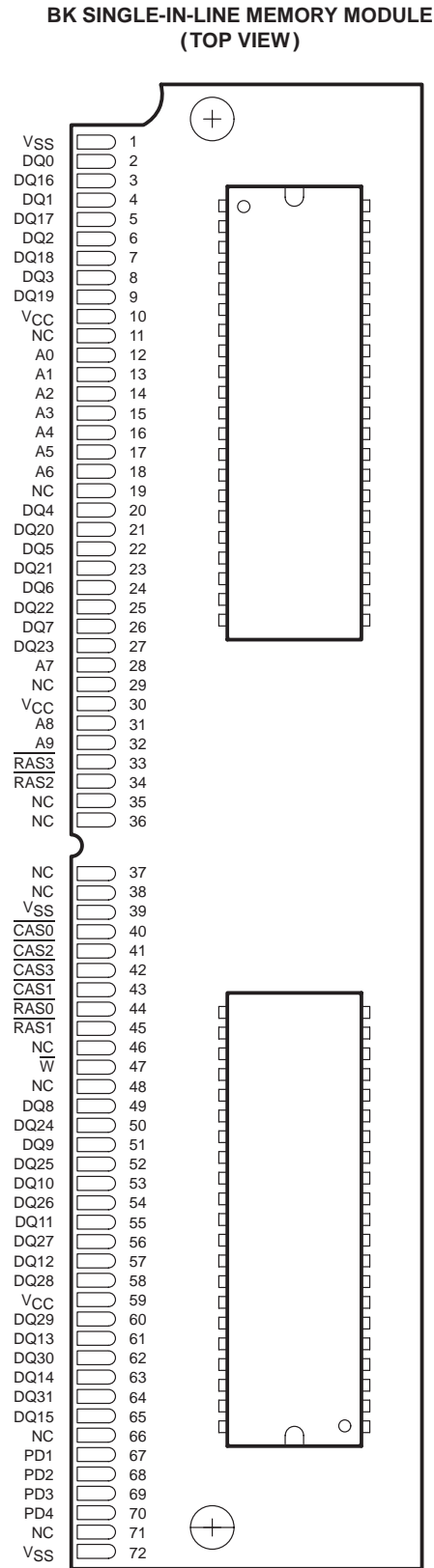
operation

The TM124BBK32F operates as two TMS418160DZs connected as shown in the functional block diagram and Table 1. The TM248CBK32F operates as four TMS418160DZs connected as shown in the functional block diagram and Table 1. The common I/O feature dictates the use of early-write cycles to prevent contention on D and Q.

[†] Part numbers in this data sheet are for the gold-tabbed version; the information applies to both gold-tabbed and solder-tabbed versions.

TM124BBK32F, TM124BBK32U 1048576 BY 32-BIT DYNAMIC RAM MODULE
TM248CBK32F, TM248CBK32U 2097152 BY 32-BIT DYNAMIC RAM MODULE

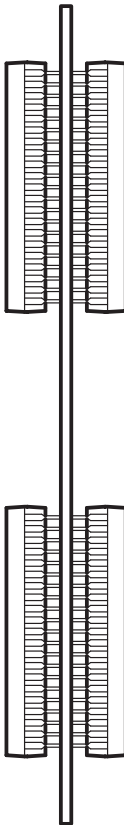
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TM124BBK32F
(SIDE VIEW)



TM248CBK32F
(SIDE VIEW)



PIN NOMENCLATURE	
A0–A9	Address Inputs
CAS0–CAS3	Column-Address Strobe
DQ0–DQ31	Data In/Data Out
NC	No Connection
PD1–PD4	Presence Detects
RAS0–RAS3	Row-Address Strobe
VCC	5-V Supply
VSS	Ground
W	Write Enable

PRESENCE DETECT					
SIGNAL (PIN)		PD1 (67)	PD2 (68)	PD3 (69)	PD4 (70)
TM124BBK32F	80 ns	VSS	VSS	NC	VSS
	70 ns	VSS	VSS	VSS	NC
	60 ns	VSS	VSS	NC	NC
TM248CBK32F	80 ns	NC	NC	NC	VSS
	70 ns	NC	NC	VSS	NC
	60 ns	NC	NC	NC	NC

Table 1. Connection Table

DATA BLOCK	RASx		CASx
	SIDE 1	SIDE 2†	
DQ0–DQ7	RAS0	RAS1	CAS0
DQ8–DQ15	RAS0	RAS1	CAS1
DQ16–DQ23	RAS2	RAS3	CAS2
DQ24–DQ31	RAS2	RAS3	CAS3

† Side 2 applies to the TM248CBK32F only.

single-in-line memory module and components

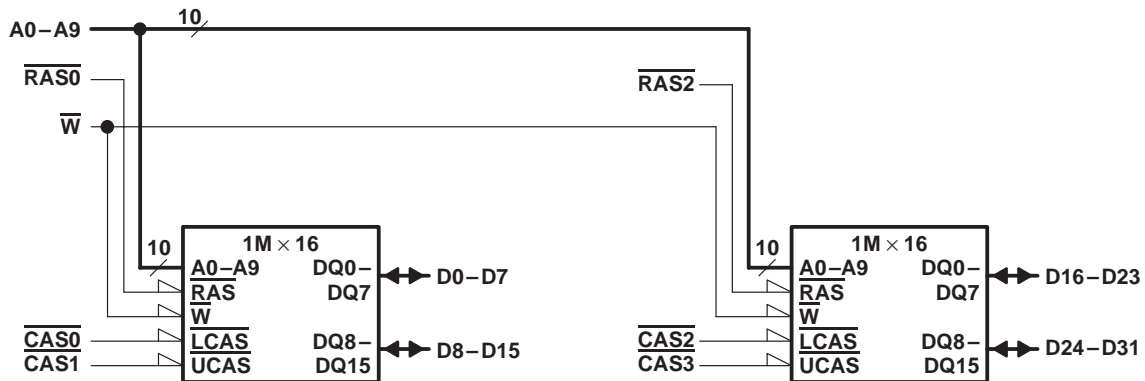
PC substrate: $1,27 \pm 0,1$ mm (0.05 inch) nominal thickness; 0.005 inch/inch maximum warpage

Bypass capacitors: Multilayer ceramic

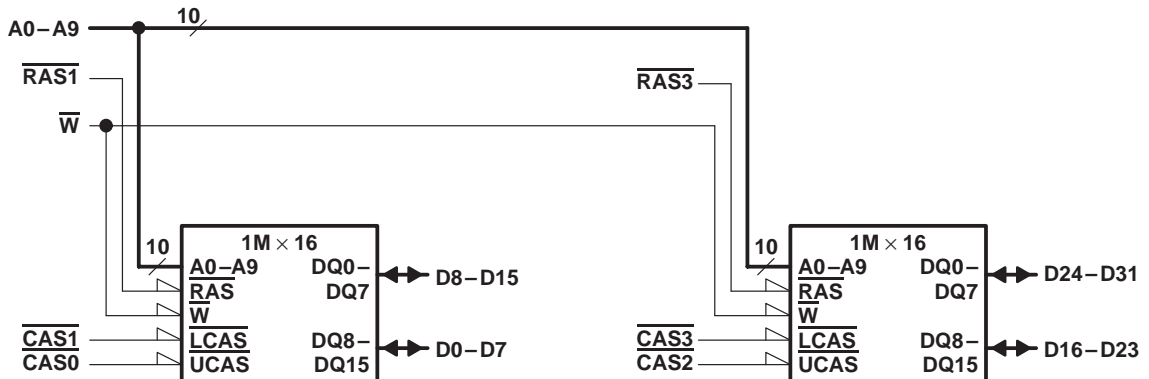
Contact area for TM124BBK32F and TM248CBK32F: Nickel plate and gold plate over copper

Contact area for TM124BBK32U and TM248CBK32U: Nickel plate and tin/lead over copper

functional block diagram (TM124BBK32F and TM248CBK32F, side 1)



functional block diagram (TM248CBK32F, side 2)



TM124BBK32F, TM124BBK32U 1048576 BY 32-BIT DYNAMIC RAM MODULE TM248CBK32F, TM248CBK32U 2097152 BY 32-BIT DYNAMIC RAM MODULE

SMMS649A – DECEMBER 1994 – REVISED JUNE 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} (see Note 1)	– 1 V to 7 V
Voltage range on any pin (see Note 1)	– 1 V to 7 V
Short-circuit output current	50 mA
Power dissipation: TM124BBK32F, TM124BBK32U	2 W
TM248CBK32F, TM248CBK32U	4 W
Operating free-air temperature range, T_A	0°C to 70°C
Storage temperature range, T_{stg}	– 55°C to 125°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to V_{SS} .

recommended operating conditions

	MIN	NOM	MAX	UNIT
V_{CC} Supply voltage	4.5	5	5.5	V
V_{IH} High-level input voltage	2.4		6.5	V
V_{IL} Low-level input voltage (see Note 2)	– 1		0.8	V
T_A Operating free-air temperature	0		70	°C

NOTE 2: The algebraic convention, where the more negative (less positive) limit is designated as minimum, is used for logic-voltage levels only.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	'124BBK32F-60		'124BBK32F-70		'124BBK32F-80		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
V_{OH} High-level output voltage	$I_{OH} = -5$ mA	2.4		2.4		2.4		V
V_{OL} Low-level output voltage	$I_{OL} = 4.2$ mA		0.4		0.4		0.4	V
I_I Input current (leakage)	$V_{CC} = 5.5$ V, $V_I = 0$ V to 6.5 V, All other pins = 0 V to V_{CC}		± 10		± 10		± 10	µA
I_O Output current (leakage)	$V_{CC} = 5.5$ V, $V_O = 0$ V to V_{CC} , \overline{CAS} high		± 10		± 10		± 10	µA
I_{CC1} Read- or write-cycle current	$V_{CC} = 5.5$ V, Minimum cycle		180		160		140	mA
I_{CC2} Standby current	$V_{IH} = 2.4$ V (TTL), After 1 memory cycle, \overline{RAS} and \overline{CAS} high		4		4		4	mA
	$V_{IH} = V_{CC} - 0.2$ V (CMOS), After 1 memory cycle, \overline{RAS} and \overline{CAS} high		2		2		2	mA
I_{CC3} Average refresh current (RAS only or CBR)	$V_{CC} = 5.5$ V, Minimum cycle, \overline{RAS} cycling, \overline{CAS} high (RAS only); \overline{RAS} low after \overline{CAS} low (CBR)		180		160		140	mA
I_{CC4} Average page current	$V_{CC} = 5.5$ V, $t_{PC} = \text{MIN}$, \overline{RAS} low, \overline{CAS} cycling		180		160		140	mA



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TM124BBK32F, TM124BBK32U 1048576 BY 32-BIT DYNAMIC RAM MODULE
TM248CBK32F, TM248CBK32U 2097152 BY 32-BIT DYNAMIC RAM MODULE

SMMS649A – DECEMBER 1994 – REVISED JUNE 1995

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)†

PARAMETER	TEST CONDITIONS	'248CBK32F-60		'248CBK32F-70		'248CBK32F-80		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
V _{OH}	High-level output voltage	I _{OH} = – 5 mA		2.4		2.4		V
V _{OL}	Low-level output voltage	I _{OL} = 4.2 mA		0.4		0.4		V
I _I	Input current (leakage)	V _{CC} = 5.5 V, V _I = 0 V to 6.5 V, All other pins = 0 V to V _{CC}		± 10		± 10		µA
I _O	Output current (leakage)	V _{CC} = 5.5 V, V _O = 0 V to V _{CC} , $\overline{\text{CAS}}$ high		± 20		± 20		µA
I _{CC1}	Read- or write-cycle current (see Note 3)	V _{CC} = 5.5 V, Minimum cycle		184		164		mA
I _{CC2}	Standby current	V _{IH} = 2.4 V (TTL), After 1 memory cycle, $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ high		8		8		mA
		V _{IH} = V _{CC} – 0.2 V (CMOS), After 1 memory cycle, $\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ high		4		4		mA
I _{CC3}	Average refresh current ($\overline{\text{RAS}}$ only or CBR) (see Note 3)	V _{CC} = 5.5 V, Minimum cycle, $\overline{\text{RAS}}$ cycling, $\overline{\text{CAS}}$ high ($\overline{\text{RAS}}$ only); $\overline{\text{RAS}}$ low after $\overline{\text{CAS}}$ low (CBR)		360		320		mA
I _{CC4}	Average page current (see Note 4)	V _{CC} = 5.5 V, t _{PC} = MIN, $\overline{\text{RAS}}$ low, $\overline{\text{CAS}}$ cycling		184		164		mA

† For test conditions shown as MIN/MAX, use the appropriate value specified under recommended operating conditions.

- NOTES: 3. Measured with a maximum of one address change while $\overline{\text{RAS}}$ = V_{IL}
4. Measured with a maximum of one address change while $\overline{\text{CAS}}$ = V_{IH}

capacitance over recommended ranges of supply voltage and operating free-air temperature, f = 1 MHz (see Note 5)

PARAMETER		'124BBK32F		'248CBK32F		UNIT
		MIN	MAX	MIN	MAX	
C _{i(A)}	Input capacitance, A0–A9	10		20		pF
C _{i(R)}	Input capacitance, $\overline{\text{RAS}}$ inputs	7		7		pF
C _{i(C)}	Input capacitance, $\overline{\text{CAS}}$ inputs	7		14		pF
C _{i(W)}	Input capacitance, $\overline{\text{W}}$	14		28		pF
C _{o(DQ)}	Output capacitance on DQ0–DQ31	7		14		pF

NOTE 5: V_{CC} = 5 V ± 0.5 V, and the bias on pins under test is 0 V.



TM124BBK32F, TM124BBK32U 1048576 BY 32-BIT DYNAMIC RAM MODULE TM248CBK32F, TM248CBK32U 2097152 BY 32-BIT DYNAMIC RAM MODULE

SMMS649A – DECEMBER 1994 – REVISED JUNE 1995

switching characteristics over recommended ranges of supply voltage and operating free-air temperature

PARAMETER	'124BBK32F-60 '248CBK32F-60		'124BBK32F-70 '248CBK32F-70		'124BBK32F-80 '248CBK32F-80		UNIT
	MIN	MAX	MIN	MAX	MIN	MAX	
t _{AA} Access time from column address		30		35		40	ns
t _{CAC} Access time from $\overline{\text{CAS}}$ low		15		18		20	ns
t _{RAC} Access time from $\overline{\text{RAS}}$ low		60		70		80	ns
t _{CPA} Access time from column precharge		35		40		45	ns
t _{CLZ} $\overline{\text{CAS}}$ to output in low-impedance state	0		0		0		ns
t _{OH} Output disable time from start of $\overline{\text{CAS}}$ high	3		3		3		ns
t _{OFF} Output disable time after $\overline{\text{CAS}}$ high (see Note 6)	0	15	0	18	0	20	ns

NOTE 6: t_{OFF} is specified when the output is no longer driven.

timing requirements over recommended ranges of supply voltage and operating free-air temperature

	'124BBK32F-60 '248CBK32F-60		'124BBK32F-70 '248CBK32F-70		'124BBK32F-80 '248CBK32F-80		UNIT
	MIN	MAX	MIN	MAX	MIN	MAX	
t _{RC} Cycle time, random read or write (see Note 7)	110		130		150		ns
t _{RWC} Cycle time, read-write	155		181		205		ns
t _{PC} Cycle time, page-mode read or write (see Notes 7 and 8)	40		45		50		ns
t _{RASP} Pulse duration, page mode, $\overline{\text{RAS}}$ low	60	100 000	70	100 000	80	100 000	ns
t _{RAS} Pulse duration, nonpage mode, $\overline{\text{RAS}}$ low	60	10 000	70	10 000	80	10 000	ns
t _{CAS} Pulse duration, $\overline{\text{CAS}}$ low	15	10 000	18	10 000	20	10 000	ns
t _{CP} Pulse duration, $\overline{\text{CAS}}$ high	10		10		10		ns
t _{RP} Pulse duration, $\overline{\text{RAS}}$ high (precharge)	40		50		60		ns
t _{WP} Pulse duration, $\overline{\text{W}}$ low	10		10		10		ns
t _{ASC} Setup time, column address before $\overline{\text{CAS}}$ low	0		0		0		ns
t _{ASR} Setup time, row address before $\overline{\text{RAS}}$ low	0		0		0		ns
t _{DS} Setup time, data before $\overline{\text{CAS}}$ low	0		0		0		ns
t _{RCS} Setup time, $\overline{\text{W}}$ high before $\overline{\text{CAS}}$ low	0		0		0		ns
t _{CWL} Setup time, $\overline{\text{W}}$ low before $\overline{\text{CAS}}$ high	15		18		20		ns
t _{RWL} Setup time, $\overline{\text{W}}$ low before $\overline{\text{RAS}}$ high	15		18		20		ns
t _{WCS} Setup time, $\overline{\text{W}}$ low before $\overline{\text{CAS}}$ low	0		0		0		ns
t _{WRP} Setup time, $\overline{\text{W}}$ high before $\overline{\text{RAS}}$ low (CBR refresh only)	10		10		10		ns
t _{CAH} Hold time, column address after $\overline{\text{CAS}}$ low	10		15		15		ns
t _{RHCP} Hold time, $\overline{\text{RAS}}$ high from $\overline{\text{CAS}}$ precharge	35		40		45		ns
t _{DH} Hold time, data after $\overline{\text{CAS}}$ low	10		15		15		ns
t _{RAH} Hold time, row address after $\overline{\text{RAS}}$ low	10		10		10		ns
t _{RCH} Hold time, $\overline{\text{W}}$ high after $\overline{\text{CAS}}$ high (see Note 9)	0		0		0		ns
t _{RRH} Hold time, $\overline{\text{W}}$ high after $\overline{\text{RAS}}$ high (see Note 9)	0		0		0		ns

NOTES: 7. All cycles assume t_T = 5 ns.

8. To assure t_{PC} min, t_{ASC} should be ≥ t_{CP}.

9. Either t_{RRH} or t_{RCH} must be satisfied for a read cycle.



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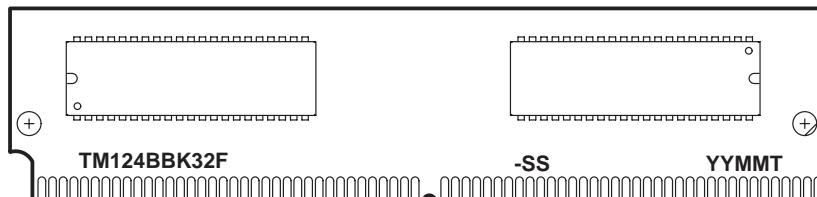
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timing requirements over recommended ranges of supply voltage and operating free-air temperature (continued)

		'124BBK32F-60 '248CBK32F-60		'124BBK32F-70 '248CBK32F-70		'124BBK32F-80 '248CBK32F-80		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
tWCH	Hold time, \overline{W} low after \overline{CAS} low	10		15		15		ns
tWRH	Hold time, \overline{W} high after \overline{RAS} low (CBR refresh only)	10		10		10		ns
tCHR	Delay time, \overline{RAS} low to \overline{CAS} high (CBR refresh only)	10		10		10		ns
tCRP	Delay time, \overline{CAS} high to \overline{RAS} low	5		5		5		ns
tCSH	Delay time, \overline{RAS} low to \overline{CAS} high	60		70		80		ns
tCSR	Delay time, \overline{CAS} low to \overline{RAS} low (CBR refresh only)	5		5		5		ns
tRAD	Delay time, \overline{RAS} low to column address (see Note 10)	15	30	15	35	15	40	ns
tRAL	Delay time, column address to \overline{RAS} high	30		35		40		ns
tCAL	Delay time, column address to \overline{CAS} high	30		35		40		ns
tRCD	Delay time, \overline{RAS} low to \overline{CAS} low (see Note 10)	20	45	20	52	20	60	ns
tRPC	Delay time, \overline{RAS} high to \overline{CAS} low (CBR only)	0		0		0		ns
tRSH	Delay time, \overline{CAS} low to \overline{RAS} high	15		18		20		ns
tREF	Refresh time interval		16		16		16	ms
tT	Transition time	3	30	3	30	3	30	ns

NOTE 10: The maximum value is specified only to assure access time.

device symbolization (TM124BBK32F illustrated)



YY = Year Code
 MM = Month Code
 T = Assembly Site Code
 -SS = Speed Code

NOTE: Location of symbolization may vary.



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SMMS649A – DECEMBER 1994 – REVISED JUNE 1995



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